

Title (en)

CONTACT APPARATUS FOR MINIMIZING THE LOAD OF MECHANICALLY LOADED SMT SOLDERED JOINTS

Title (de)

KONTAKTVORRICHTUNG ZUR BELASTUNGSMINIMIERUNG MECHANISCH BEANSPRUCHTER SMT-LÖTSTELLEN

Title (fr)

DISPOSITIF DE CONTACT DESTINE A MINIMISER LA CHARGE DE ZONES DE BRASAGE SMT SOLLICITEES PAR DES CONTRAINTES MECANIQUES

Publication

EP 1889334 B1 20110420 (DE)

Application

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Priority

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Abstract (en)

[origin: US2009130869A1] At least one embodiment of the invention relates to a contact apparatus for SMT placement on a printed circuit board, the contact apparatus being provided for the electrically conductive connection to at least one conductor track on the printed circuit board. The contact apparatus includes a contact holder for accommodating the contact, and the contact of the contact apparatus is provided for the connection to at least one electrical mating contact. The contact apparatus is designed on an SMT basis and can therefore be produced inexpensively and fitted easily. According to at least one embodiment of the invention, the contact apparatus has a first housing part, the housing part having at least one elongate cutout for accommodating the contact holder, and at least one stop for the contact being integrally formed on the housing part, which stop is provided for the purpose of absorbing insertion forces when contact is made between the contact and an electrical mating contact.

IPC 8 full level

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